

SOLDER PASTE

LEAD-FREE HIGH TEMPERATURE SOLDER PASTE



Sn99/Ag0.3/Cu0.7

Melting point 217°C



Product Usage



TIN PASTE

Model	BST-705A
Name	Lead-free high temperature solder paste
Composition	Sn99/Ag0.3/Cu0.7
Melting point	217°C
G.W.	50g
Granule	20~38μm
Size	φ50*16mm

Sn99/Ag0.3/Cu0.7

Lead-free high temperature melting point

217°C





Low residue

Fine grain

Rapid welding

Solder spot bright

Welding requirements for a wide range of products



SMT
patch



LED
patch



BGA
welding

Product Size



G.W.:50g

